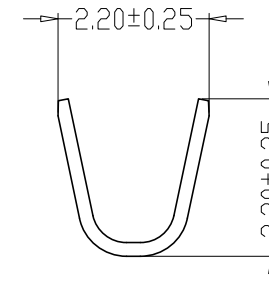
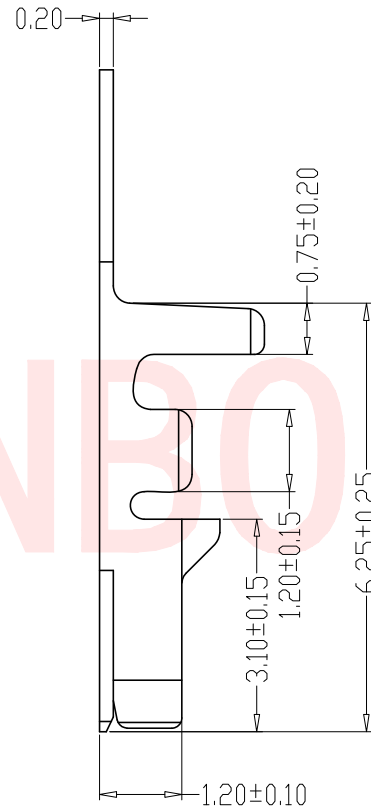
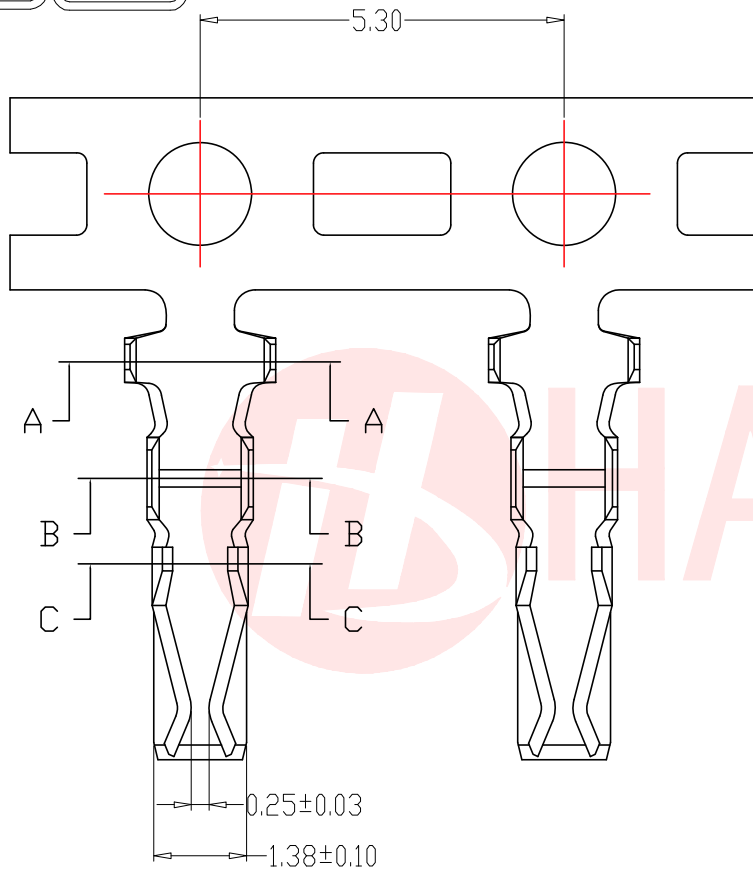
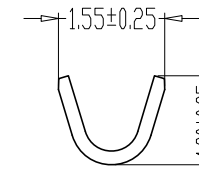




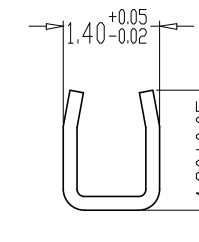
REV.	ECN NO OR DESCRIPTION	REVISED	DATE



SEC:A-A



SEC:B-B



SEC:C-C

SPECIFICATIONS

- 1、Current Rating: 2A AC, DC
- 2、Voltage Rating: 250V AC, DC
- 3、Temperatuer Range: -25°C~+85°C
- 4、Contact Resistance: 20mΩ Max
- 5、Insulation Resistance: 1000MΩ Min
- 6、Withstanding Voltang: 1000V AC/minute
- 7、Material:Phosphoric bronze Tin-plated
- 8、Applicable Wire Sizes:AWG#24~30#

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.20	X :±2°
X.X :±0.10	X.X :±1°
X.XX :±0.05	



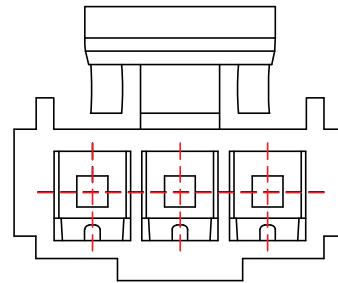
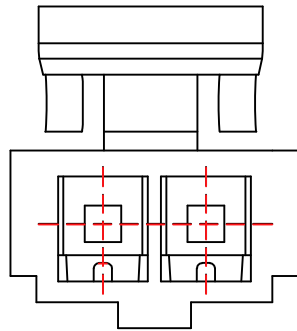
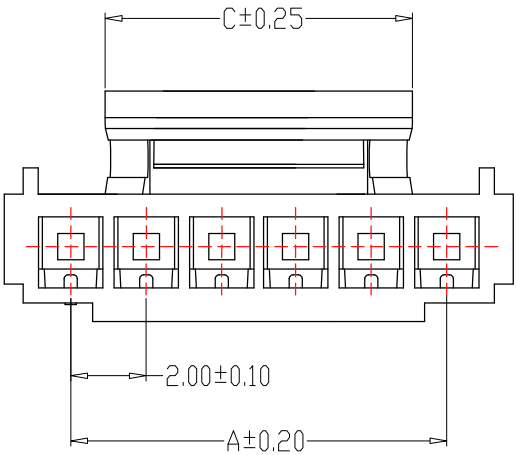
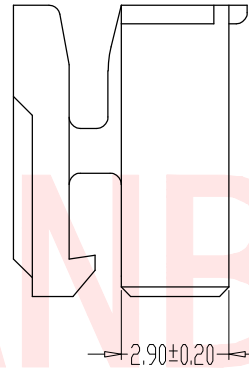
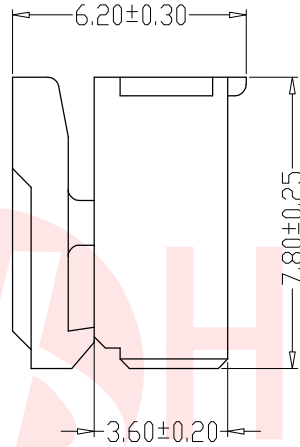
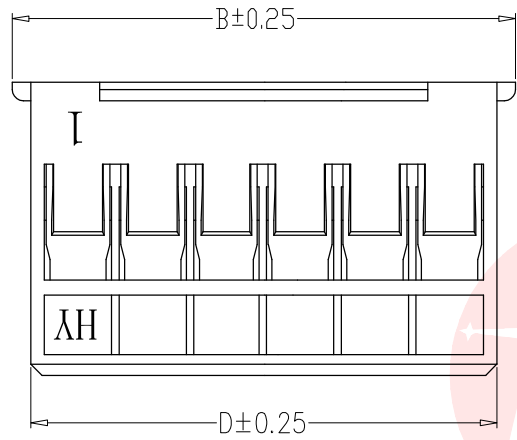
东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	WAFER HY 2.00端子		
DWN	xiong	PART NO. WAFER-HY200DZ	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1

CUSTOMER COPY



REV.	ECN NO OR DESCRIPTION	REVISED	DATE



SPECIFICATIONS

- 1、Current Rating: 2A AC, DC
- 2、Voltage Rating: 250V AC, DC
- 3、Temperatuer Range: -25°C~+85°C
- 4、Contact Resistance: 20mΩ Max
- 5、Insulation Resistance: 1000MΩ Min
- 6、Withstanding Voltang: 1000V AC/minute
- 7、Material:Housing:Nylon66, UL94V-0

TABLE:

CSG PART NO.	PIN位	A	B	C	D
WAFER-HY200JK-2A	2PIN	2.00	5.50	3.20	4.55
WAFER-HY200JK-3A	3PIN	4.00	7.50	3.20	6.55
WAFER-HY200JK-4A	4PIN	6.00	9.50	4.30	8.55
WAFER-HY200JK-5A	5PIN	8.00	11.50	4.30	10.55
WAFER-HY200JK-6A	6PIN	10.00	13.50	8.30	12.55
WAFER-HY200JK-7A	7PIN	12.00	15.50	10.30	14.55
WAFER-HY200JK-8A	8PIN	14.00	17.50	12.30	16.55
WAFER-HY200JK-9A	9PIN	16.00	19.50	12.30	18.55
WAFER-HY200JK-10A	10PIN	18.00	21.50	12.30	20.55
WAFER-HY200JK-11A	11PIN	20.00	23.50	16.30	22.55
WAFER-HY200JK-12A	12PIN	22.00	25.50	16.30	24.55
WAFER-HY200JK-17A	17PIN	32.00	35.50	16.30	34.55
WAFER-HY200JK-18A	18PIN	34.00	37.50	16.30	36.55
WAFER-HY200JK-19A	19PIN	36.00	39.50	16.30	38.55
WAFER-HY200JK-20A	20PIN	38.00	41.50	16.30	40.55

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X :±0.20
X.X :±0.10
X.XX :±0.05

ANGLES: X :±2°
X.X :±1°



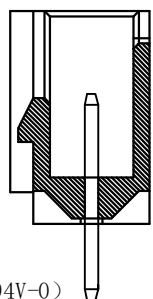
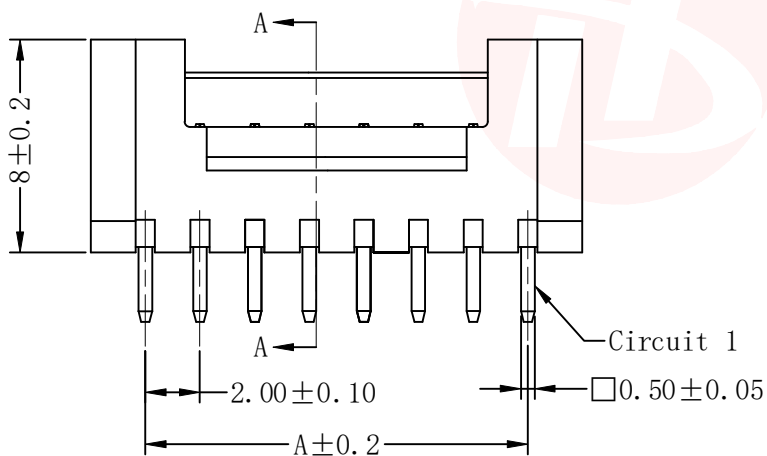
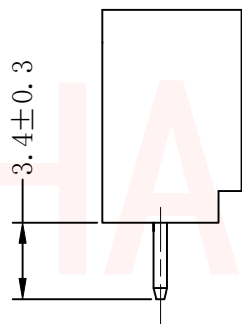
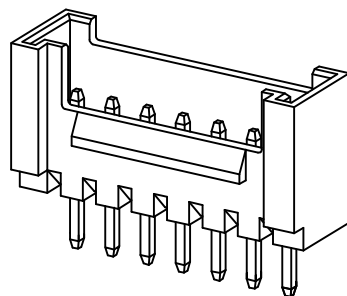
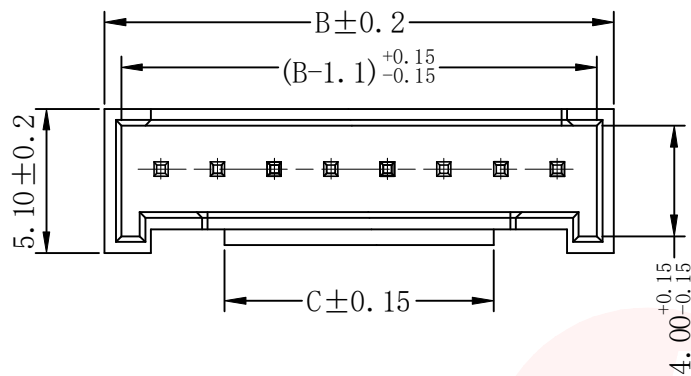
东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	WAFER HY 2.00 胶壳		
DWN	xiong	PART NO. WAFER-HY200JK-NA	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1
REV: A4			

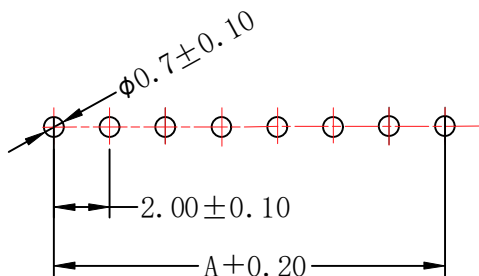
CUSTOMER COPY



REV.	ECN NO OR DESCRIPTION	REVISED	DATE



SECTION A-A



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

- 技术要求:
- 1、塑件材料: LCP/PA66 (UL-94V-0)
 - 2、接触件: 黄铜镀锡
 - 3、接触电阻: $\leq 10\text{m}\Omega$
 - 4、绝缘电阻: $\geq 1000\text{M}\Omega$
 - 5、额定电压: 250V AC DC
 - 6、额定电流: 2.0A AC DC
 - 7、耐压: 能承受1000V AC/Minute
 - 8、工作温度: $-25^{\circ}\text{C} \sim +85^{\circ}\text{C}$
 - 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $220^{\pm 5^{\circ}}$, 时间 2.5 ± 0.5 秒
 - 10、铅和镉等六大有害物质含量要符合环保要求

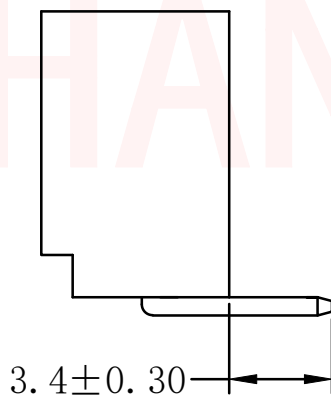
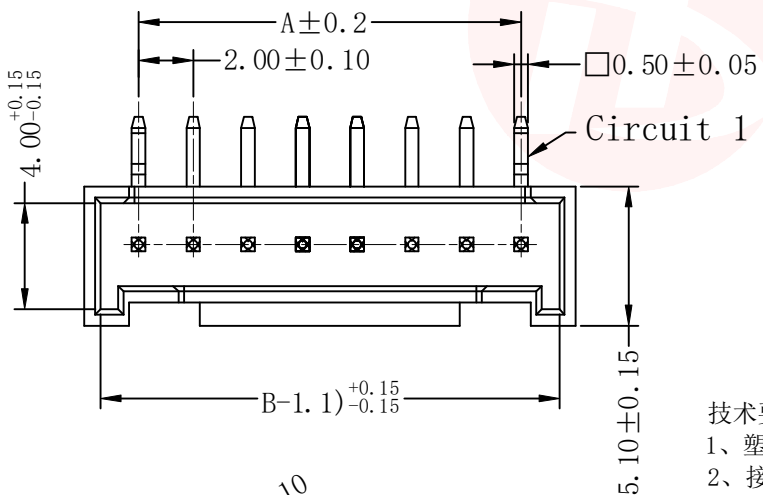
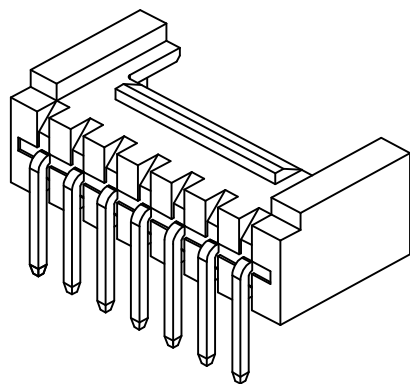
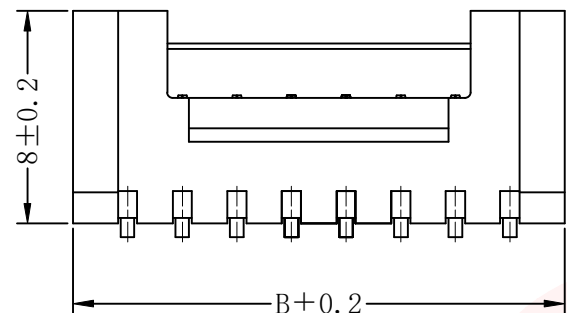
TABLE:

CSG PART NO.	Dimension mm			
	PIN	A	B	C
WAFER-HY200Z-2A	2P	2.00	6.00	2.50
WAFER-HY200Z-3A	3P	4.00	8.00	2.50
WAFER-HY200Z-4A	4P	6.00	10.00	3.50
WAFER-HY200Z-5A	5P	8.00	12.00	5.50
WAFER-HY200Z-6A	6P	10.00	14.00	7.50
WAFER-HY200Z-7A	7P	12.00	16.00	9.50
WAFER-HY200Z-8A	8P	14.00	18.00	11.50
WAFER-HY200Z-9A	9P	16.00	20.00	13.50
WAFER-HY200Z-10A	10P	18.00	22.00	15.50
WAFER-HY200Z-11A	11P	20.00	24.00	15.50
WAFER-HY200Z-12A	12P	22.00	26.00	15.50
WAFER-HY200Z-13A	13P	24.00	28.00	15.50
WAFER-HY200Z-14A	14P	26.00	30.00	15.50
WAFER-HY200Z-15A	15P	28.00	32.00	15.50

序号	名称	材料	电镀(锡): 整个表面镀底锡 30U"MIN 再镀锡80U" MIN
1	端子/Contact	黄铜	
2	基座/Wafer	LCP/PA66 (UL94V-0)	白色
UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD	
DECIMALS: ANGLES:		TITLE: WAFER HY 2.0MM 直针 DIP TYPE	
X : ±0.20	X : ±2°	DWN	xiong PART NO. WAFER-HY200Z-NA
X.X : ±0.10	X.X : ±1°	CHKD	lee SCALE:1:1 UNIT: mm
X.XX : ±0.05		APVD	wang SIZE: A4 SHEET:10F 1 REV: A4
CUSTOMER COPY			



REV.	ECN NO OR DESCRIPTION	REVISED	DATE

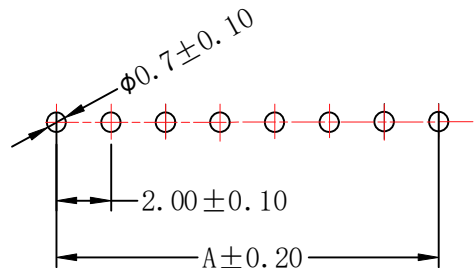


技术要求:

- 1、塑件材料: LCP/PA66 (UL-94V-0)
- 2、接触件: 黄铜镀锡
- 3、接触电阻: $\leq 10m\Omega$
- 4、绝缘电阻: $\geq 1000M\Omega$
- 5、额定电压: 250V AC DC
- 6、额定电流: 2.0A AC DC
- 7、耐压: 能承受1000V AC/Minute
- 8、工作温度: $-25^{\circ} \sim +85^{\circ}$
- 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度 220^{+5}_{0} , 时间 2.5 ± 0.5 秒
- 10、铅和镉等六大有害物质含量要符合环保要求

TABLE:

CSG PART NO.	Dimension mm			
	PIN	A	B	C
WAFER-HY200WZ-2A	2P	2.00	6.00	2.50
WAFER-HY200WZ-3A	3P	4.00	8.00	2.50
WAFER-HY200WZ-4A	4P	6.00	10.00	3.50
WAFER-HY200WZ-5A	5P	8.00	12.00	5.50
WAFER-HY200WZ-6A	6P	10.00	14.00	7.50
WAFER-HY200WZ-7A	7P	12.00	16.00	9.50
WAFER-HY200WZ-8A	8P	14.00	18.00	11.50
WAFER-HY200WZ-9A	9P	16.00	20.00	13.50
WAFER-HY200WZ-10A	10P	18.00	22.00	15.50
WAFER-HY200WZ-11A	11P	20.00	24.00	15.50
WAFER-HY200WZ-12A	12P	22.00	26.00	15.50
WAFER-HY200WZ-13A	13P	24.00	28.00	15.50
WAFER-HY200WZ-14A	14P	26.00	30.00	15.50
WAFER-HY200WZ-15A	15P	28.00	32.00	15.50



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

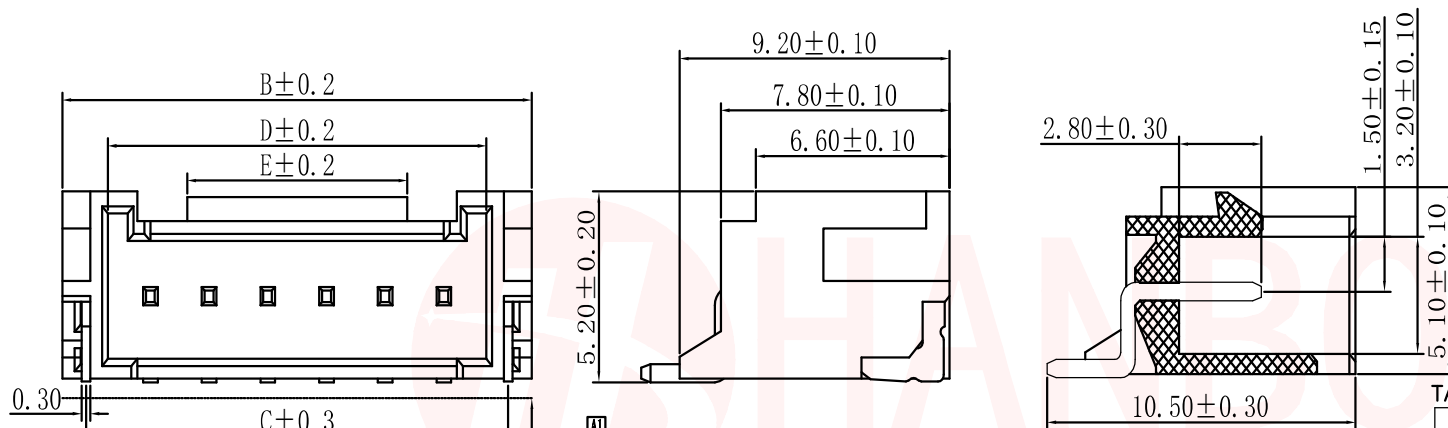
序号	名称	材料	电镀(锡): 整个表面镀底镍 30U"MIN 再镀锡80U" MIN
1	端子/Contact	黄铜	
2	基座/Wafer	LCP/PA66 (UL94V-0)	白色
UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD	
DECIMALS: ANGLES:		TITLE: WAFER HY 2.0MM 弯针 DIP TYPE	
X : ±0.20	X : ±2°	DWN	xiong PART NO. WAFER-HY200WZ-NA
X.X : ±0.10	X.X : ±1°	CHKD	lee SCALE:1:1 UNIT: mm
X.XX : ±0.05		APVD	wang SIZE: A4 SHEET:10F 1 REV: A4
CUSTOMER COPY			



REV.	ECN NO OR DESCRIPTION	REVISED	DATE

SPECIFICATIONS

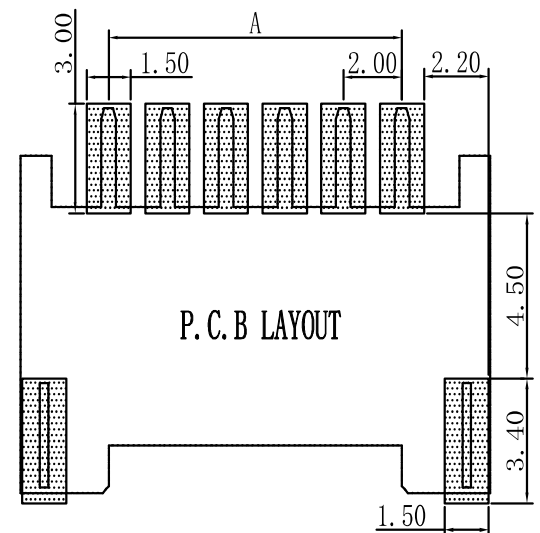
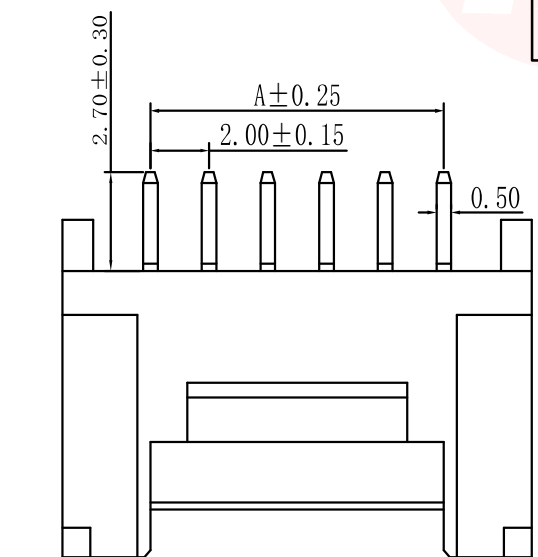
- 1、Current Rating: 2A AC, DC
- 2、Voltage Rating: 250V AC, DC
- 3、Temperatuer Range: -25°C~+85°C
- 4、Contact Resistance: 20mΩ Max
- 5、Insulation Resistance: 1000MΩ Min
- 6、Withstanding Voltang: 1000V AC/minute
- 7、Material: Wafer LCP, UL94V-0
PIN Brass Tin-plated
Solder tad Brass Tin-plated



AL			
02P-10P	0.10	MAX	
11P-16P	0.12	MAX	

TABLE:

CSG PART NO.	Dimension mm				
	A	B	C	D	E
WAFER-HY200W-2A	2.00	8.00	6.50	4.90	2.50
WAFER-HY200W-3A	4.00	10.00	8.50	6.90	3.00
WAFER-HY200W-4A	6.00	12.00	10.50	8.90	5.00
WAFER-HY200W-5A	8.00	14.00	12.50	10.90	7.00
WAFER-HY200W-6A	10.00	16.00	14.50	12.90	9.00
WAFER-HY200W-7A	12.00	18.00	16.50	14.90	11.00
WAFER-HY200W-8A	14.00	20.00	18.50	16.90	13.00
WAFER-HY200W-9A	16.00	22.00	20.50	18.90	15.00
WAFER-HY200W-10A	18.00	24.00	22.50	20.90	17.00
WAFER-HY200W-11A	20.00	26.00	24.50	22.90	19.00
WAFER-HY200W-12A	22.00	28.00	26.50	24.90	21.00
WAFER-HY200W-13A	24.00	30.00	28.50	26.90	23.00
WAFER-HY200W-14A	26.00	32.00	30.50	28.90	25.00
WAFER-HY200W-15A	28.00	34.00	32.50	30.90	27.00
WAFER-HY200W-16A	30.00	36.00	34.50	32.90	29.00



UNLESS OTHERWISE SPECIFIED TOLERANCES

东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

DECIMALS: X :±0.25
X.X :±0.20
X.XX :±0.15

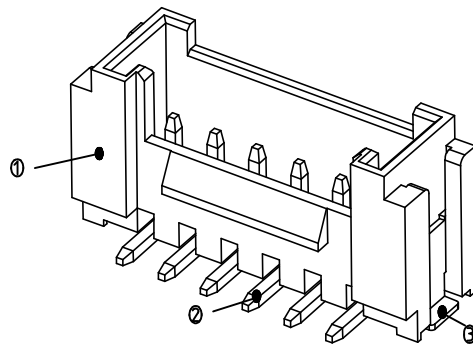
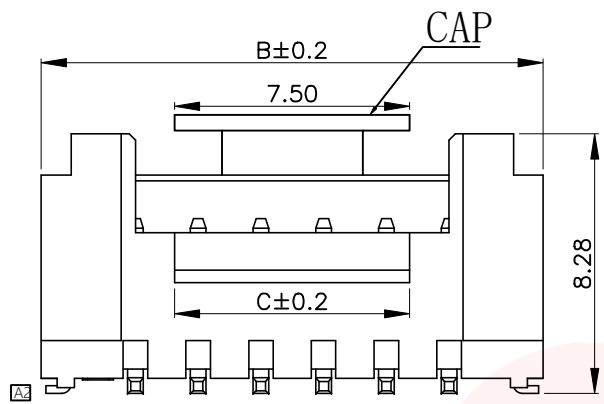
ANGLES: X :±2°
X.X :±1°

TITLE	WAFER HY 2.0 贴片带卡扣 SMT TYPE			
DWN	xiong	PART NO. WAFER-HY200W-NA		
CHKD	lee	SCALE:1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET:10F 1	REV: A4

CUSTOMER COPY



REV.	ECN NO OR DESCRIPTION	REVISED	DATE



SPECIFICATIONS

- 1、Current Rating: 2A AC, DC
 - 2、Voltage Rating: 250V AC, DC
 - 3、Temperatuer Range: -25℃~+85℃
 - 4、Contact Resistance: 20mΩ Max
 - 5、Insulation Resistance: 1000MΩ Min
 - 6、Withstanding Voltang: 1000V AC/minute
 - 7、Material: Wafer LCP, UL94V-0
- PIN Brass Tin-plated
Solder Brass Tin-plated

	02P-10P	0.10	MAX
	11P-16P	0.12	MAX

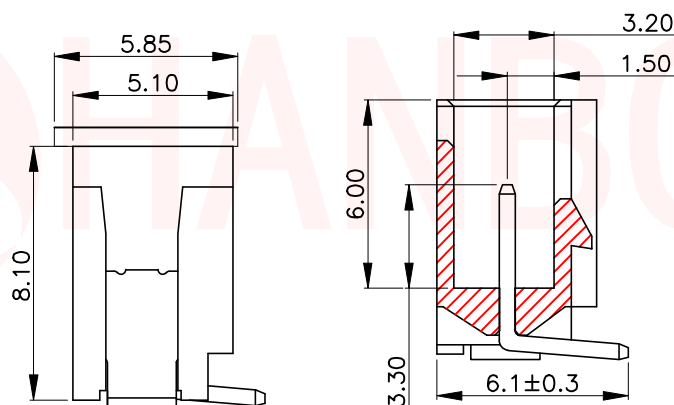
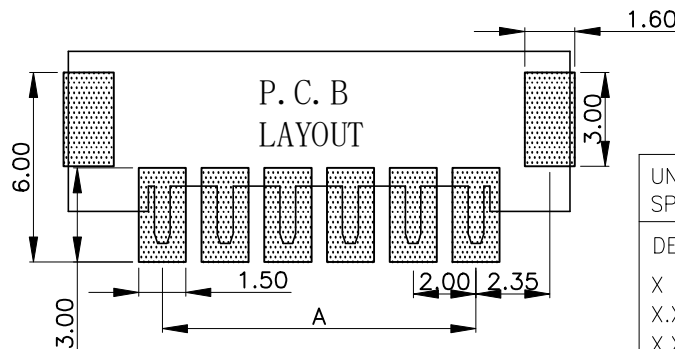
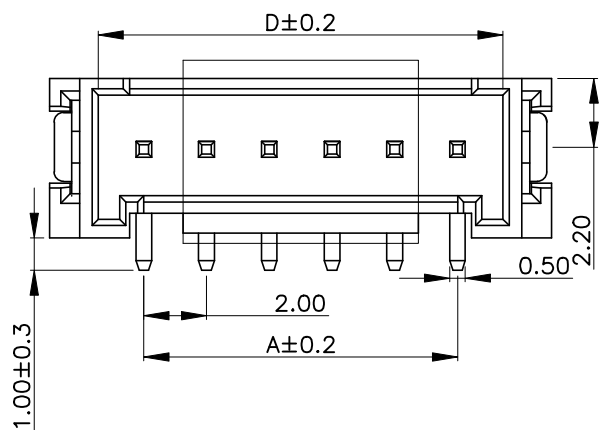


TABLE:

CSG PART NO.	Dimension mm			
	A	B	C	D
WAFER-HY200L-2A	2.00	8.00	2.50	4.90
WAFER-HY200L-3A	4.00	10.00	2.50	6.90
WAFER-HY200L-4A	6.00	12.00	5.00	8.90
WAFER-HY200L-5A	8.00	14.00	7.00	10.90
WAFER-HY200L-6A	10.00	16.00	9.00	12.90
WAFER-HY200L-7A	12.00	18.00	11.00	14.90
WAFER-HY200L-8A	14.00	20.00	13.00	16.90
WAFER-HY200L-9A	16.00	22.00	15.00	18.90
WAFER-HY200L-10A	18.00	24.00	17.00	20.90
WAFER-HY200L-11A	20.00	26.00	19.00	22.90
WAFER-HY200L-12A	22.00	28.00	21.00	24.90
WAFER-HY200L-13A	24.00	30.00	23.00	26.90
WAFER-HY200L-14A	26.00	32.00	25.00	28.90
WAFER-HY200L-15A	28.00	34.00	27.00	30.90
WAFER-HY200L-16A	30.00	36.00	29.00	32.90



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X ±0.25
X.X ±0.20
X.XX ±0.15

ANGLES: X ±2°
X.X ±1°



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	WAFER HY 2.0 贴片 SMT TYPE		
DWN	xiong	PART NO. WAFER-HY200L-NA	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1

CUSTOMER COPY